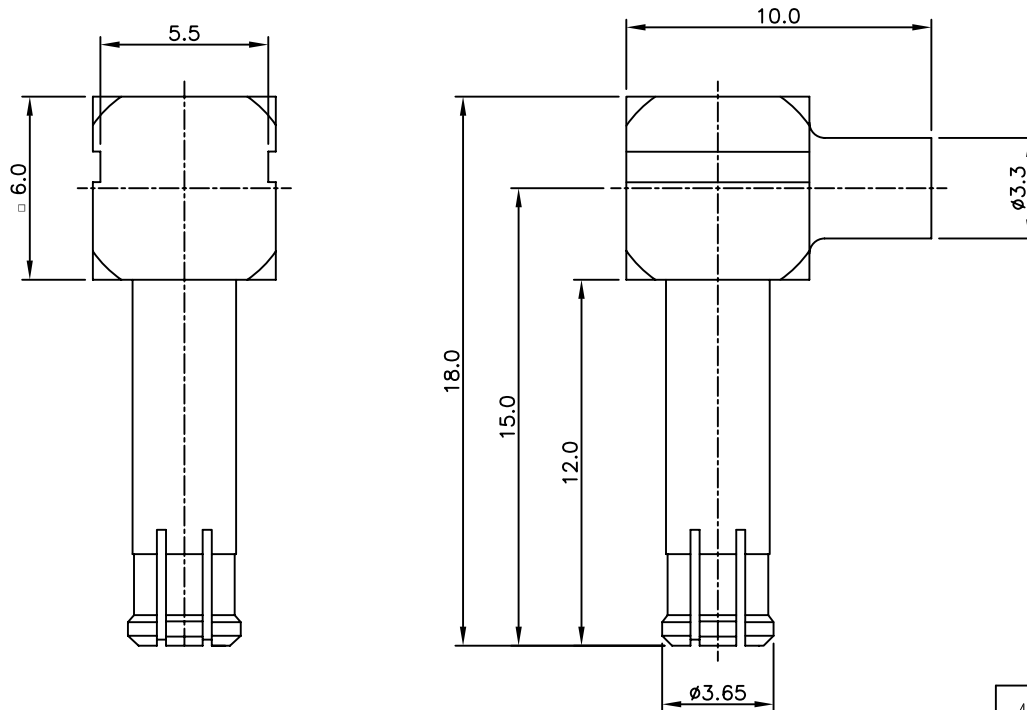


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	E.H.KIM	I.C.KIM	2014.09.11.
1	[설번No.202002-0003] solder부 TRU->ST 형상 변경 및 JACK 커팅깊이, 납시바늘 추가	S.Y.EUN	I.C.KIM	2020.02.12.



4	COVER	1	MBsBD	Gold Plate	DCO00011-5/1
3	INSULATOR	1	TEFLON		DIN01317-N/1
2	CONTACT	1	MBsBD	Gold Plate	DCT01572-5/1
1-2	JACK BODY	1	BeCu	Gold Plate	DJA00113-5/3
1-1	BODY	1	MBsBD	Gold Plate	DBB00158-3/3
					DBD02051-5/2
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2020. 02. 12.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL	-	CHECKED BY		KJ COMTECH CO.,LTD. TITLE MCX50 CABLE LP 85
		DRAWN BY	S.Y.EUN	
FINISH	-	SCALE	4/1	 A4
		UNIT	mm	
		DWG NO.	CN02047-7/2	SHEET 1 of 1
		REVISION	1	